



Material Content Data Sheet



Sales Product Name		BTS3060TF		Issued		20. July 2018		
MA#		MA001220394						
Package		PG-TO252-3-11		Weight*		389.80 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.041	0.27	0.27	2670	2670
leadframe	non noble metal	iron	7439-89-6	0.140	0.04		359	
	inorganic material	phosphorus	7723-14-0	0.042	0.01		108	
	non noble metal	copper	7440-50-8	139.706	35.84	35.89	358404	358871
wire	non noble metal	aluminium	7429-90-5	0.486	0.12	0.12	1246	1246
encapsulation	organic material	carbon black	1333-86-4	1.487	0.38		3815	
	plastics	epoxy resin	-	26.024	6.68		66763	
	inorganic material	silicondioxide	60676-86-0	121.199	31.09	38.15	310926	381504
leadfinish	non noble metal	tin	7440-31-5	3.740	0.96	0.96	9595	9595
plating	non noble metal	nickel	7440-02-0	0.091	0.02		233	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.02	1	234
solder	noble metal	silver	7440-22-4	0.031	0.01		79	
	non noble metal	tin	7440-31-5	0.025	0.01		63	
	non noble metal	lead	7439-92-1	1.177	0.30	0.32	3020	3162
heatspreader	non noble metal	iron	7439-89-6	0.095	0.02		243	
	inorganic material	phosphorus	7723-14-0	0.028	0.01		73	
	non noble metal	copper	7440-50-8	94.488	24.24	24.27	242402	242718
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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